



Click [here](#) for the 3D model.

### Dimensions

Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
T	1.6mm +/-0.15mm
S	2.9mm MIN
B	0.7mm +/-0.35mm

### Packaging Specifications

Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	4000

### General Information

Series	SMD Comm COG HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Ultra-Stable
Features	FT-CAP, Ultra-Stable
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
Termination	Flexible Termination With Lead (SnPb)
Marking	false
AEC-Q200	No
Typical Component Weight	81 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	1000 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms